

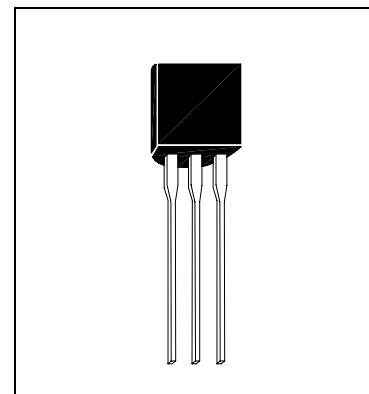


H2N5366

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The H2N5366 is designed for general purpose applications requiring high breakdown voltages.



Features

- This device was designed for use as general purpose amplifier and switches.

Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 400 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage -40 V
VCEO Collector to Emitter Voltage -40 V
VEBO Emitter to Base Voltage -4 V
IC Collector Current -500 mA

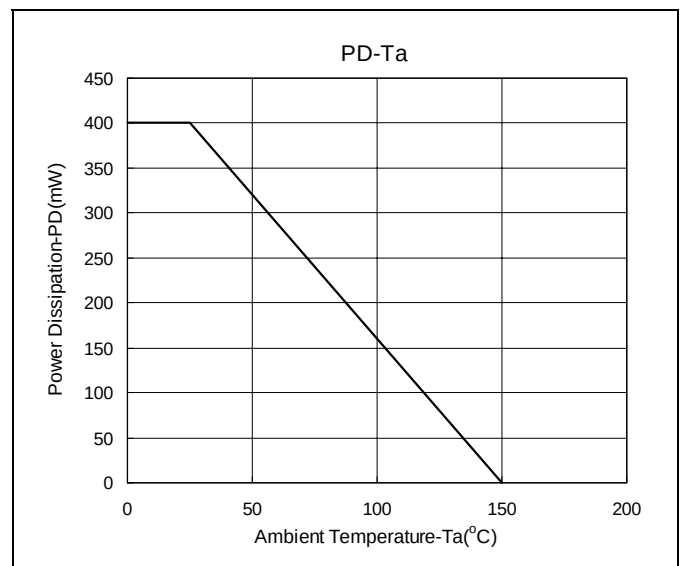
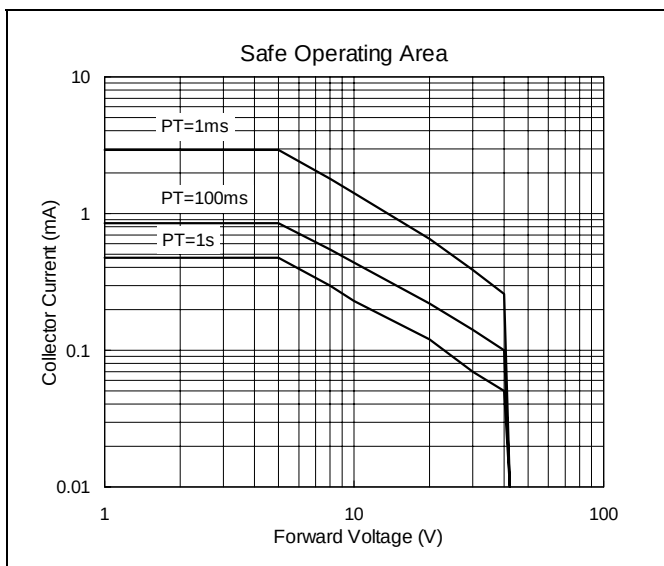
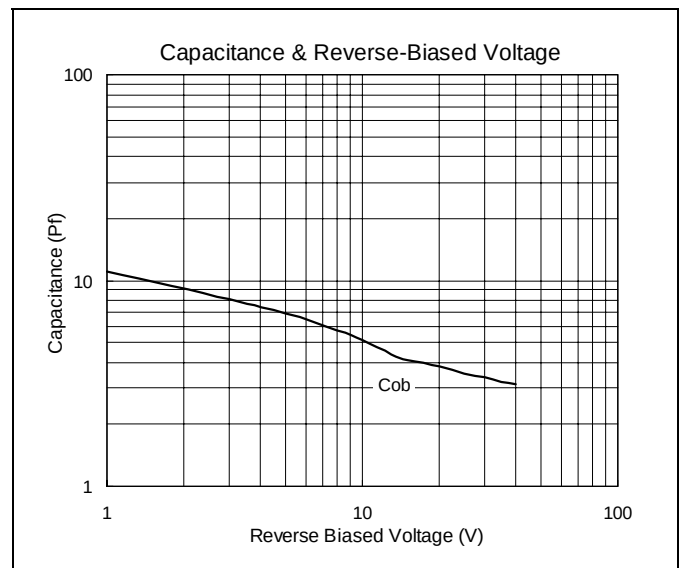
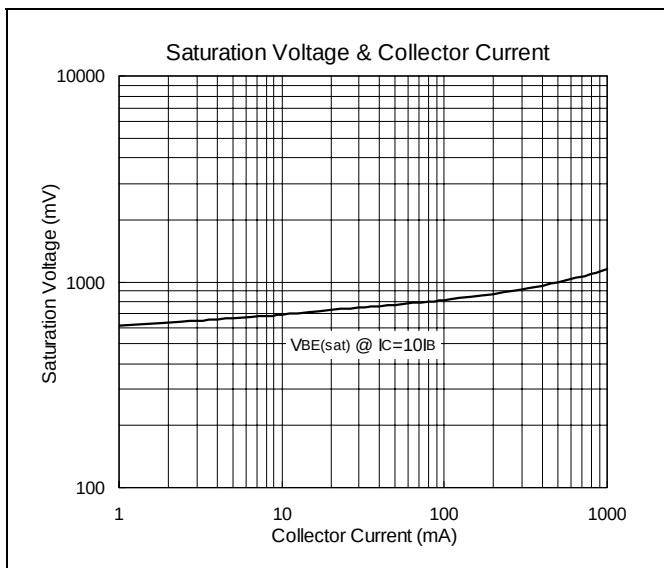
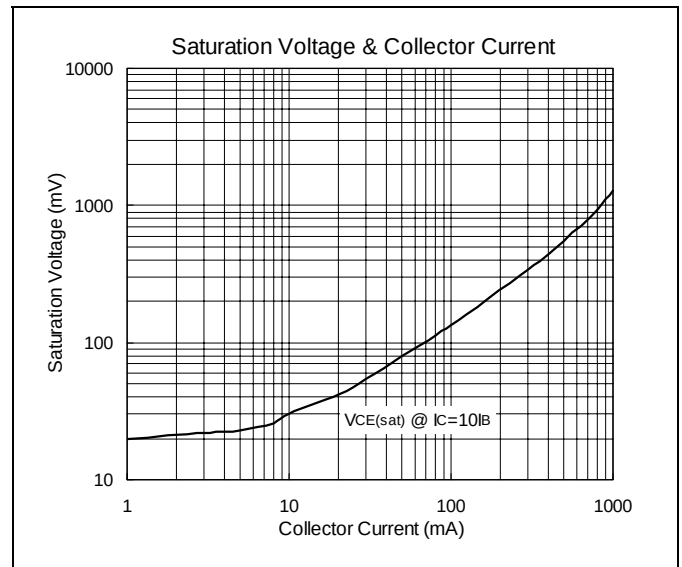
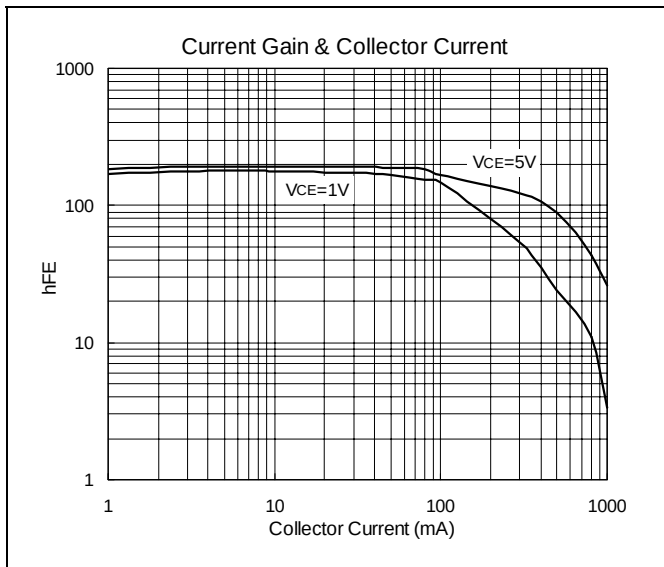
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-40	-	-	V	IC=-100uA, IE=0
BVCEO	-40	-	-	V	IC=-1mA, IB=0
BVEBO	-4	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-100	nA	VCB=-45V, IE=0
IEBO	-	-	-100	nA	VEB=-3V, IC=0
*VCE(sat)1	-	-	-250	mV	IC=-50mA, IB=-5mA
*VCE(sat)2	-	-	-1	V	IC=-300mA, IB=-30mA
*VBE(sat)1	-	-	-1.1	V	IC=-50mA, IB=-5mA
*VBE(sat)2	-	-	-2	V	IC=-300mA, IB=-30mA
*hFE1	80	-	-		VCE=-1V, IC=-2mA
*hFE2	100	-	-		VCE=-1V, IC=-50mA
*hFE3	40	-	-		VCE=-5V, IC=-300mA
fT	-	-	-	MHz	VCE=-10V, IC=-10mA, f=100MHz
Cob	-	-	10	PF	VCB=-10V, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

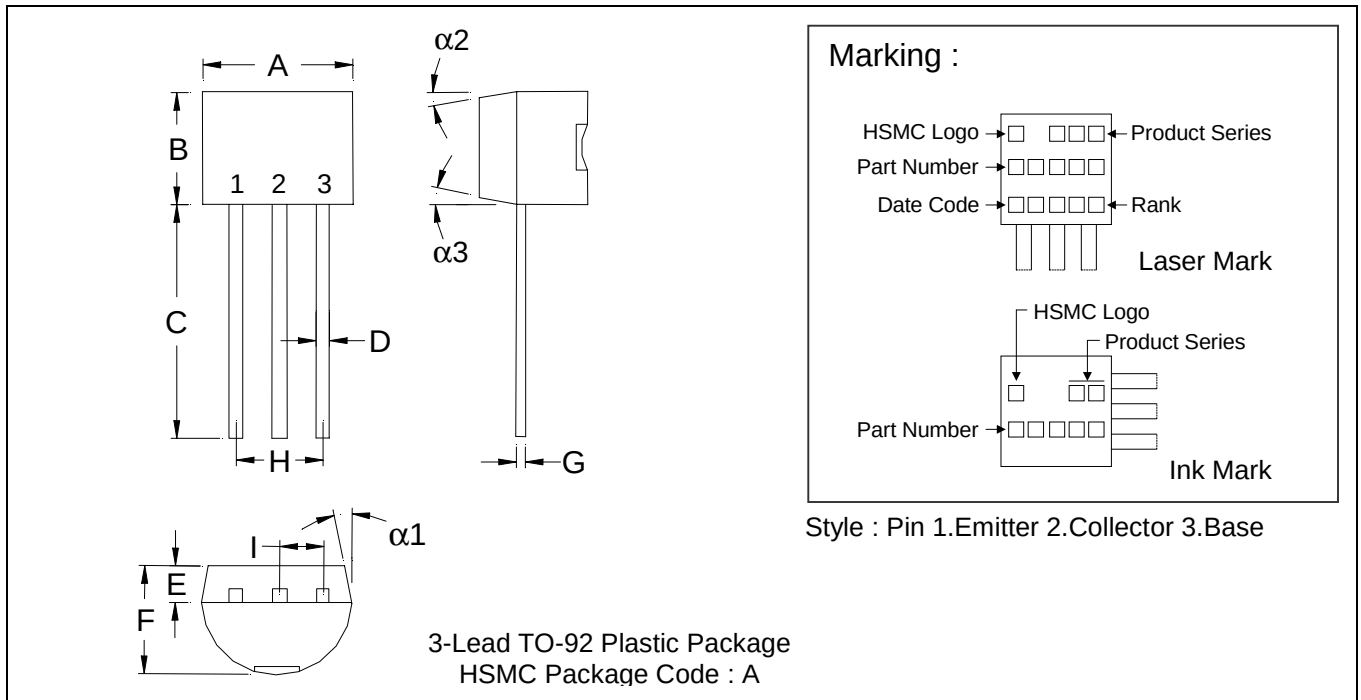


Characteristics Curve





TO-92 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1** : No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel : 886-3-5983621~5 Fax : 886-3-5982931
- **Factory 2** : No. 17-1, Ta-Tung Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel : 886-3-5977061 Fax : 886-3-5979220